



Drill Map:
x 0.400mm / 0.0157" (3 holes)
o 1.000mm / 0.0394" (18 holes)

NOTES

- 1. Layer Count: 2
- 2. PCB Thickness: 0.8 mm
- 3. PCB Color: Green
- 4. Surface Finish: HASL (with lead)
- 5. Outer Copper Weight: 1 oz.
- 6. Via Covering: Tented
- 7. Board Outline Tolerance: +/-0.2mm

BOARD CHARACTERISTICS

Copper Layer Count:	2	Board Thickness:	31.50 mils
Board overall dimensions:	1900.00 mils x 835.00 mils		
Min track/spacing:	0.00 mils / 12.00 mils	Min hole diameter:	11.81 mils
Copper Finish:	None	Impedance Control:	No
Castellated pads:	No	Plated Board Edge:	No
Edge card connectors:	No		

Layer Name	Type	Material	Thickness (mils)	Color	Epsilon R	Loss Tangent
F.Silkscreen	Top Silk Screen	Not specified	0 mils	Not specified	1	0
F.Paste	Top Solder Paste		0 mils		1	0
F.Mask	Top Solder Mask	Not specified	0.3937 mils	Not specified	3.3	0
F.Cu	copper		1.37795 mils		1	0
Dielectric 1	core	FR4	27.95276 mils	Not specified	4.5	0.02
B.Cu	copper		1.37795 mils		1	0
B.Mask	Bottom Solder Mask	Not specified	0.3937 mils	Not specified	3.3	0
B.Paste	Bottom Solder Paste		0 mils		1	0
B.Silkscreen	Bottom Silk Screen	Not specified	0 mils	Not specified	1	0